industry presentation

February 9th, 2022   5:00 p.m. ET   https://umich.zoom.us/j/94689195867
passcode: Broadcom

Embedded Memory R&D Overview and New Hire Opportunities

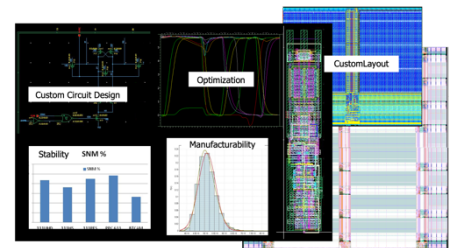**BROADCOM®**
Gordon Priebe
Roy Carlson

Abstract – Please join Gordon and Roy from Broadcom's Central Engineering Memory Development organization to learn about Broadcom Inc and the challenges of embedded memory development. As a leading provider of embedded memory, Broadcom has the largest portfolio of memory products and features in the industry. During this discussion you will learn about multiple Broadcom opportunities in custom memory circuit design and design automation on leading silicon process technologies.

Bio's – **Gordon Priebe** directs multiple SRAM product development teams at Broadcom's Minneapolis MN location. He has his MSEE degree from the University of Minnesota and has over 40 years of industry R&D experience. **Roy Carlson** is also from the Minneapolis MN location and leads design automation, test chip development, silicon validation, and Non-Volatile memory IP. Roy has his BSEE from the University of MN and has over 30 years of industry experience.

Broadest Industry Memory Portfolio
- Compiled & Custom Memory
- SRAM: 1P, 2P, DP, MP, XR
- RegFile: 2P, xMP, Sync, Async
- CAM, XY-TCAM, TLB
- NVM/OTP, & System Level Memory
- Extensive features across portfolio with speed/density/power options

Full Custom Circuit Design & Layout

Memory Compilers: build over 500K possible memory configurations

Param	Ex Values
#words	variable
#bits	variable
decode	side, center
cmux	2,4,8,16,32
bank	1,2,4,8
rows/bank	variable
Power Mode	LS, DS, SD
Repair	Y, N
L / VT	vt1, vt2, vt3
Pipelined	Y, N
Assist	Y, N; R, W
DFT	dft1, dft2
Repair	Y, N

Custom digital design & layout
Custom Analog design & layout

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